

Final datasheet
CoolSiC™ 1200 V SiC Trench MOSFET

Features

- $V_{DS} = 1200\text{ V}$ at $T_{vj} = -55...175^{\circ}\text{C}$
- $I_{DDC} = 69\text{ A}$ at $T_C = 25^{\circ}\text{C}$
- New performance-optimized chip technology (Gen1p) with improved $R_{DS(on)}$ * A FOM
- Increased recommended turn-on voltage ($V_{GS(on)} = 20\text{ V}$) for lower $R_{DS(on)}$
- Best-in-class switching energy for lower switching losses and reduced cooling efforts
- Lowest device capacitances for higher switching speeds and higher power density
- A combination of low C_{rss}/C_{iss} ratio and high $V_{GS(th)}$ to avoid parasitic turn-on and enable unipolar gate driving
- Reduced total gate charge Q_{Gtot} for lower driving power and losses
- .XT die attach technology for best-in-class thermal performance
- Sense pin for optimized switching performance
- Minimum creepage distance of 7.07 mm to fit HV requirements

Potential applications

- On-board charger
- DC/DC converter
- Auxiliary drives

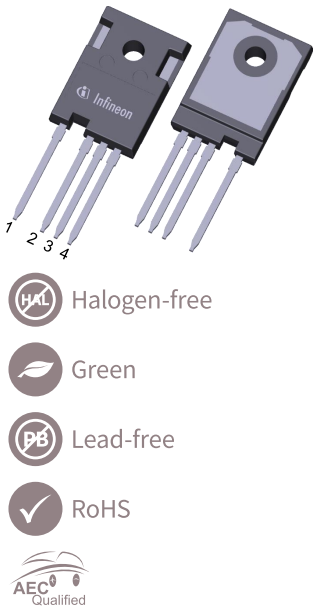
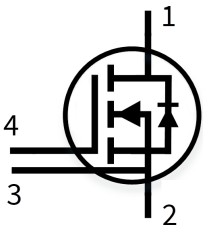
Product validation

- Qualified for Automotive Applications. Product Validation according to AEC-Q100/101

Description

Pin definition:

- 1 – drain
- 2 – source
- 3 – Kelvin sense contact
- 4 – gate



Type	Package	Marking
AIMZHN120R030M1T	PG-TO247-4-U05	A12M1N030



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1 Package

1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature	T_{sold}				260	°C
MOSFET/body diode thermal resistance, junction-case ¹⁾	$R_{th(j-c)}$			0.35	0.46	K/W

1) Not subject to production test. Parameter verified by design / characterization

2 MOSFET

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Drain-source voltage ¹⁾	V_{DSS}	$T_{vj} = -55...175\text{ °C}$		1200	V
Continuous DC drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$ ²⁾	I_{DDC}	$V_{GS} = 20\text{ V}$	$T_c = 25\text{ °C}$	69	A
			$T_c = 100\text{ °C}$	49	
Peak drain current, t_p limited by $T_{vj(max)}$ ²⁾	I_{DM}	$V_{GS} = 20\text{ V}$		176	A
Gate-source voltage, max. transient voltage ³⁾	V_{GS}	$t_p \leq 0.5\text{ }\mu\text{s}$, $D < 0.01$		-10...25	V
Gate-source voltage, max. static voltage ³⁾	V_{GS}			-5...23	V
Avalanche energy, single pulse	E_{AS}	$I_D = 20\text{ A}$, $V_{DD} = 50\text{ V}$, $L = 1.8\text{ mH}$		361	mJ
Power dissipation, limited by $T_{vj(max)}$ ²⁾	P_{tot}		$T_c = 25\text{ °C}$	326	W
			$T_c = 100\text{ °C}$	163	

1) Tested at $T_{vj}=25\text{ °C}$, verified by design/characterization over full temperature range

2) Not subject to production test. Parameter verified by design / characterization

3) **Important note:** The selection of positive and negative gate-source voltages impacts the long-term behavior of the device. The design guidelines described in Application Note AN2018-09 must be considered to ensure sound operation of the device over the planned lifetime.

Table 3 Recommended values

Parameter	Symbol	Note or test condition	Values	Unit
Recommended turn-on gate voltage	$V_{GS(on)}$		20	V
Recommended turn-off gate voltage	$V_{GS(off)}$		0	V

Table 4 **Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Drain-source on-state resistance	$R_{DS(on)}$	$I_D = 27 \text{ A}$	$T_{vj} = 25 \text{ °C}$, $V_{GS(on)} = 20 \text{ V}$		30	38	mΩ
			$T_{vj} = 100 \text{ °C}$, $V_{GS(on)} = 20 \text{ V}$		42		
			$T_{vj} = 175 \text{ °C}$, $V_{GS(on)} = 20 \text{ V}$		60		
			$T_{vj} = 25 \text{ °C}$, $V_{GS(on)} = 18 \text{ V}$		33		
Gate-source threshold voltage	$V_{GS(th)}$	$I_D = 8.6 \text{ mA}$, $V_{DS} = V_{GS}$ (tested after 1 ms pulse at $V_{GS} = 20 \text{ V}$)	$T_{vj} = 25 \text{ °C}$	3.7	4.4	5.1	V
			$T_{vj} = 175 \text{ °C}$		3.6		
Zero gate-voltage drain current	I_{DSS}	$V_{DS} = 1200 \text{ V}$, $V_{GS} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$		0.4	26	μA
			$T_{vj} = 175 \text{ °C}$		50		
Gate leakage current	I_{GSS}	$V_{DS} = 0 \text{ V}$	$V_{GS} = 25 \text{ V}$			100	nA
			$V_{GS} = -10 \text{ V}$			-100	
Forward transconductance	g_{fs}	$I_D = 27 \text{ A}$, $V_{DS} = 20 \text{ V}$			16.5		S
Short-circuit withstand time ¹⁾	t_{SC}	$V_{DD} \leq 800 \text{ V}$, $V_{DS,peak} < 1200 \text{ V}$, $T_{vj(start)} = 25 \text{ °C}$, $R_{G,ext} = 2 \text{ } \Omega$	$V_{GS(on)} = 20 \text{ V}$		1.5		μs
			$V_{GS(on)} = 18 \text{ V}$		2		
			$V_{GS(on)} = 15 \text{ V}$		2.5		
Internal gate resistance	$R_{G,int}$	$f = 1 \text{ MHz}$, $V_{AC} = 25 \text{ mV}$			2.6		Ω
Input capacitance	C_{iss}	$V_{DS} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$			1738		pF
Output capacitance	C_{oss}	$V_{DS} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$			82		pF
Reverse transfer capacitance	C_{rss}	$V_{DS} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$			4.4		pF
C_{oss} stored energy	E_{oss}	$V_{DS} = 800 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 100 \text{ kHz}$, $V_{AC} = 25 \text{ mV}$			34		μJ
Total gate charge	Q_G	$V_{DD} = 800 \text{ V}$, $I_D = 27 \text{ A}$, $V_{GS} = 0/20 \text{ V}$, turn-on pulse			57		nC
Plateau gate charge	$Q_{GS(pl)}$	$V_{DD} = 800 \text{ V}$, $I_D = 27 \text{ A}$, $V_{GS} = 0/20 \text{ V}$, turn-on pulse			15		nC
Gate-drain charge	Q_{GD}	$V_{DD} = 800 \text{ V}$, $I_D = 27 \text{ A}$, $V_{GS} = 0/20 \text{ V}$, turn-on pulse			10		nC
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 800 \text{ V}$, $I_D = 27 \text{ A}$, $V_{GS} = 0/20 \text{ V}$, $R_{GS(on)} = 2 \text{ } \Omega$, $R_{GS(off)} = 2 \text{ } \Omega$, $L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ °C}$		11		ns
			$T_{vj} = 175 \text{ °C}$		11		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rise time	t_r	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	9		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	12		
Turn-off delay time	$t_{d(off)}$	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	21		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	22		
Fall time	t_f	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	10		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}$	10		
Turn-on energy	E_{on}	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	155		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	319		
Turn-off energy	E_{off}	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	70		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	73		
Total switching energy	E_{tot}	$V_{DD} = 800 \text{ V}, I_D = 27 \text{ A},$ $V_{GS} = 0/20 \text{ V},$ $R_{GS(on)} = 2 \Omega,$ $R_{GS(off)} = 2 \Omega, L_\sigma = 33 \text{ nH}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	225		μJ
			$T_{vj} = 175 \text{ }^\circ\text{C}$	392		
Virtual junction temperature	T_{vj}		-55		175	$^\circ\text{C}$

1) verified by the design/characterization

Note: Dynamic test circuit see Fig. F.
Characteristics at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified.

3 Body diode (MOSFET)

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Drain-source voltage ¹⁾	V_{DSS}	$T_{vj} = -55...175 \text{ }^\circ\text{C}$	1200	V
Continuous reverse drain current for $R_{th(j-c,max)}$, limited by $T_{vj(max)}$ ²⁾	I_{SDC}	$T_c = 25 \text{ }^\circ\text{C}$	60	A
		$T_c = 100 \text{ }^\circ\text{C}$	36	

(table continues...)

Table 5 (continued) Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Peak reverse drain current, t_p limited by $T_{vj(max)}$ ²⁾	I_{SM}	$V_{GS} = 0\text{ V}$	61	A
		$-5\text{ V} \leq V_{GS} \leq 0\text{ V}$, $t_p = 0.3\text{ }\mu\text{s}$	80	
		$-5 \leq V_{GS} \leq 0\text{ V}$, $T_{vj} \leq 175^\circ\text{C}$; $t_p \leq 0.3\text{ ms}$ for accumulated conduction time < 5 s or $t_p \leq 1\text{ ms}$ for accumulated conduction time < 2.5 s ³⁾	207	

- 1) Tested at $T_{vj}=25^\circ\text{C}$, verified by design/characterization
2) Not subject to production test. Parameter verified by design / characterization
3) Combination of t_p and I_{SM} should not lead to $T_{vj(max)} > 175^\circ\text{C}$

Table 6 Characteristic values

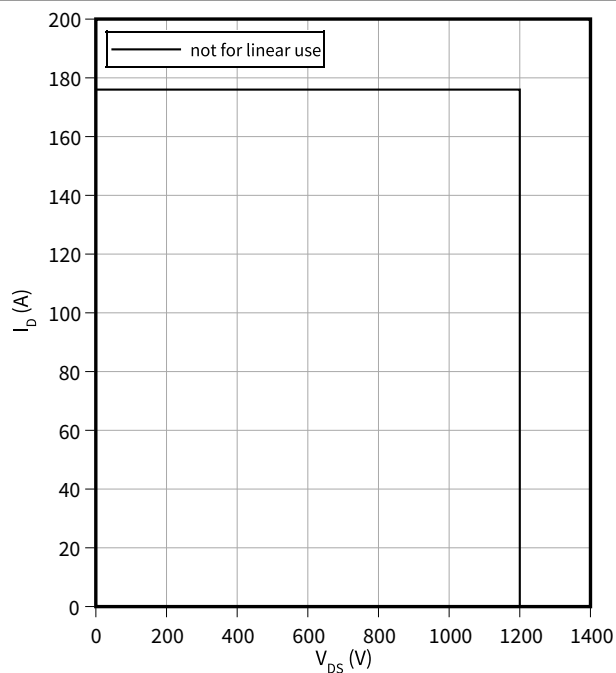
Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Drain-source reverse voltage	V_{SD}	$I_{SD} = 27\text{ A}$	$T_{vj} = 25^\circ\text{C}$	3.9	5	V
			$T_{vj} = 100^\circ\text{C}$	3.8		
			$T_{vj} = 175^\circ\text{C}$	3.7		
MOSFET forward recovery charge	Q_{fr}	$V_{DD} = 800\text{ V}$, $I_{SD} = 27\text{ A}$, $V_{GS} = 0\text{ V}$, $-di_{SD}/dt = 2000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25^\circ\text{C}$	203		nC
			$T_{vj} = 175^\circ\text{C}$	508		
MOSFET peak forward recovery current	I_{frm}	$V_{DD} = 800\text{ V}$, $I_{SD} = 27\text{ A}$, $V_{GS} = 0\text{ V}$, $-di_{SD}/dt = 2000\text{ A}/\mu\text{s}$, Q_{fr} includes also Q_C	$T_{vj} = 25^\circ\text{C}$	18		A
			$T_{vj} = 175^\circ\text{C}$	33		
Virtual junction temperature	T_{vj}		-55		175	$^\circ\text{C}$

4 Characteristics diagrams

Reverse bias safe operating area (RBSOA)

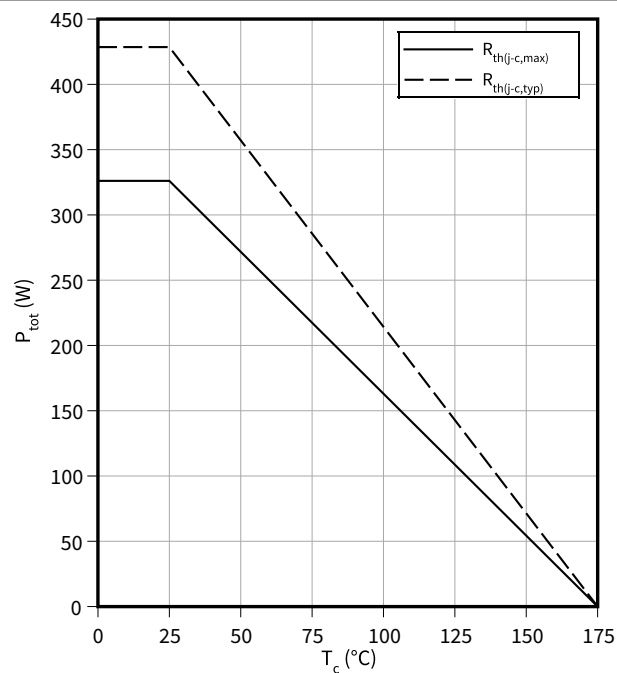
$$I_D = f(V_{DS})$$

$$T_{vj} \leq 175\text{ °C}, V_{GS} = 0/20\text{ V}, T_c = 25\text{ °C}$$



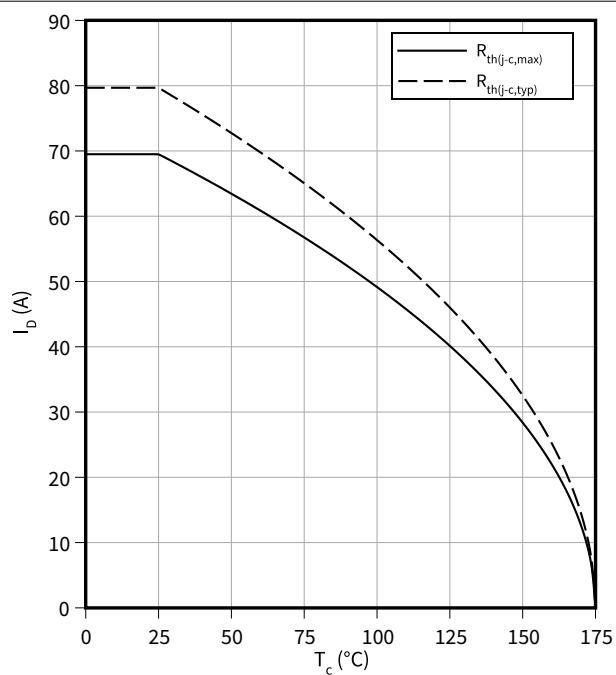
Power dissipation as a function of case temperature

$$P_{tot} = f(T_c)$$



Maximum DC drain to source current as a function of case temperature

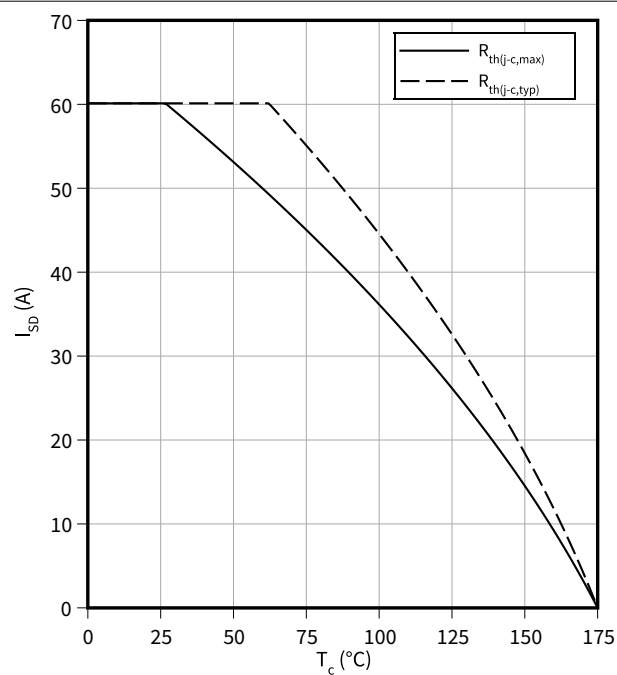
$$I_D = f(T_c)$$



Maximum source to drain current as a function of case temperature

$$I_{SD} = f(T_c)$$

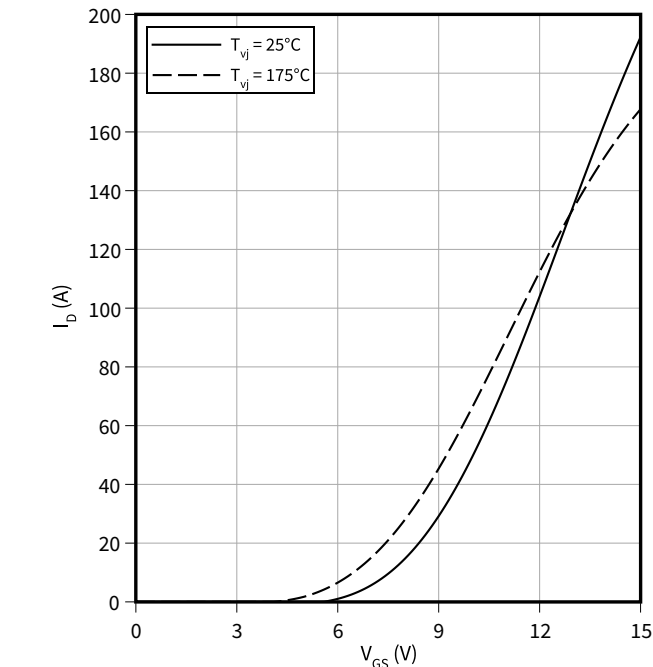
$$V_{GS} = 0\text{ V}$$



4 Characteristics diagrams

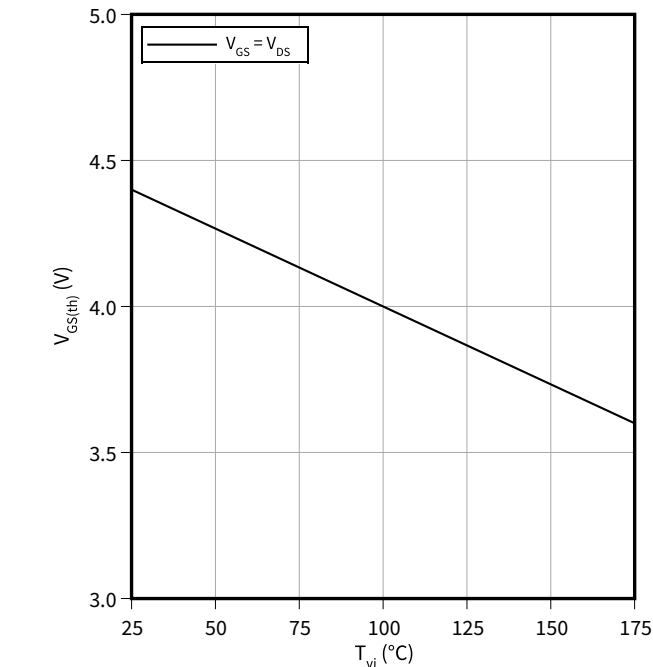
Typical transfer characteristic

$I_D = f(V_{GS})$
 $V_{DS} = 20\text{ V}, t_p = 20\text{ }\mu\text{s}$



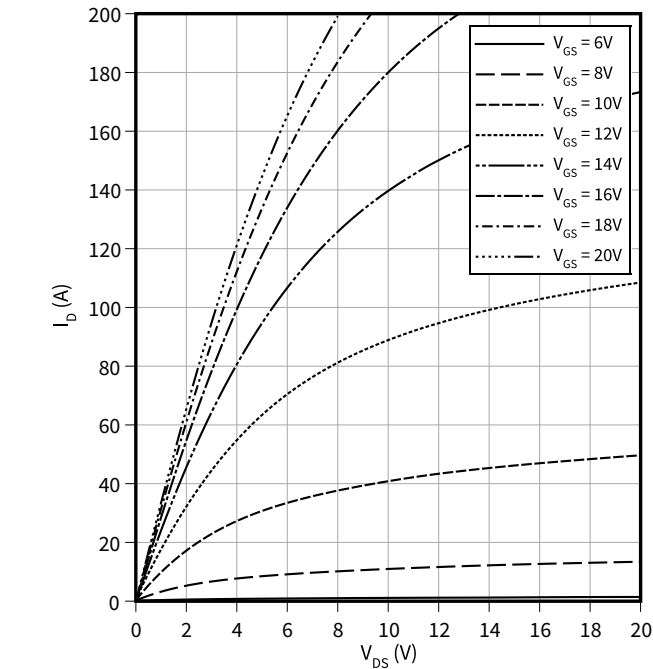
Typical gate-source threshold voltage as a function of junction temperature

$V_{GS(th)} = f(T_{vj})$
 $I_D = 8.6\text{ mA}$



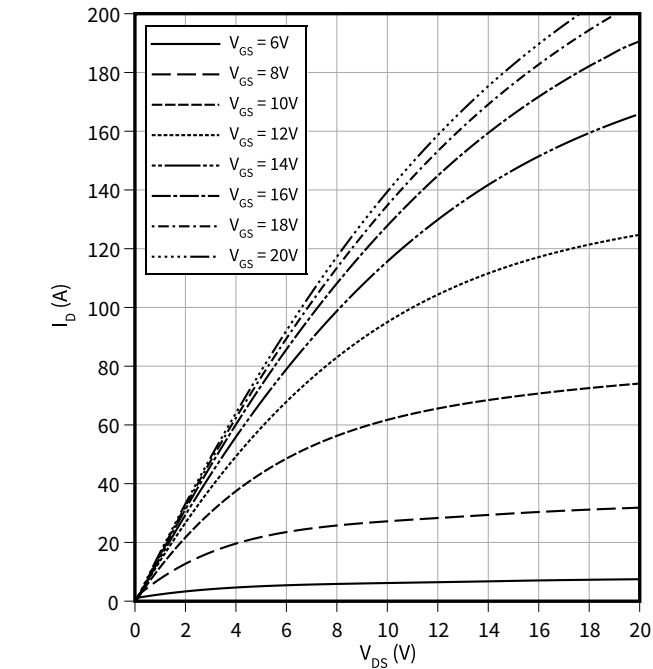
Typical output characteristic, V_{GS} as parameter

$I_D = f(V_{DS})$
 $T_{vj} = 25\text{ }^\circ\text{C}, t_p = 20\text{ }\mu\text{s}$



Typical output characteristic, V_{GS} as parameter

$I_D = f(V_{DS})$
 $T_{vj} = 175\text{ }^\circ\text{C}, t_p = 20\text{ }\mu\text{s}$

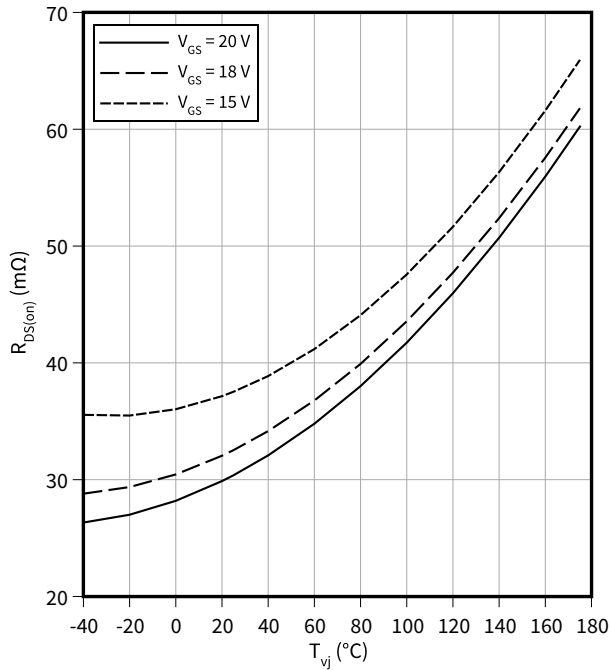


4 Characteristics diagrams

Typical on-state resistance as a function of junction temperature

$$R_{DS(on)} = f(T_{vj})$$

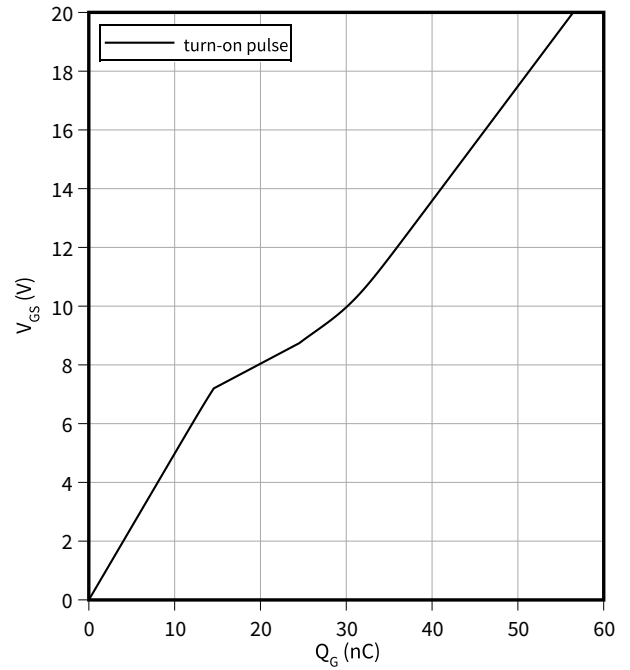
$$I_D = 27 \text{ A}$$



Typical gate charge

$$V_{GS} = f(Q_G)$$

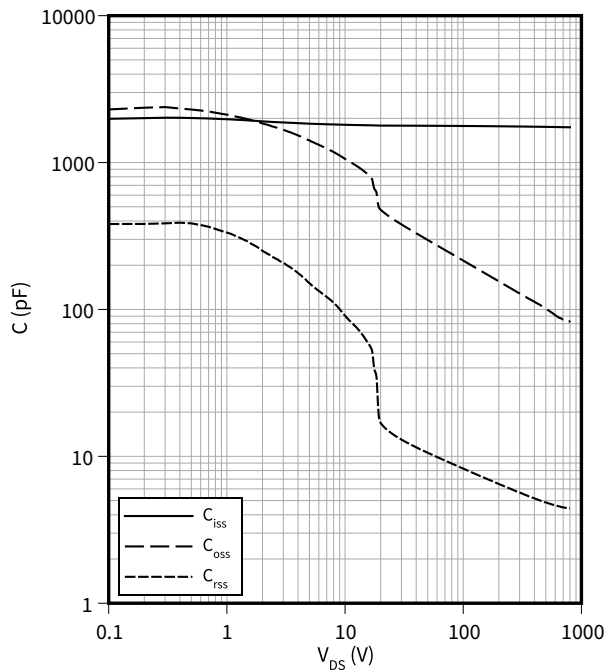
$$I_D = 27 \text{ A}, V_{DS} = 800 \text{ V}$$



Typical capacitance as a function of drain-source voltage

$$C = f(V_{DS})$$

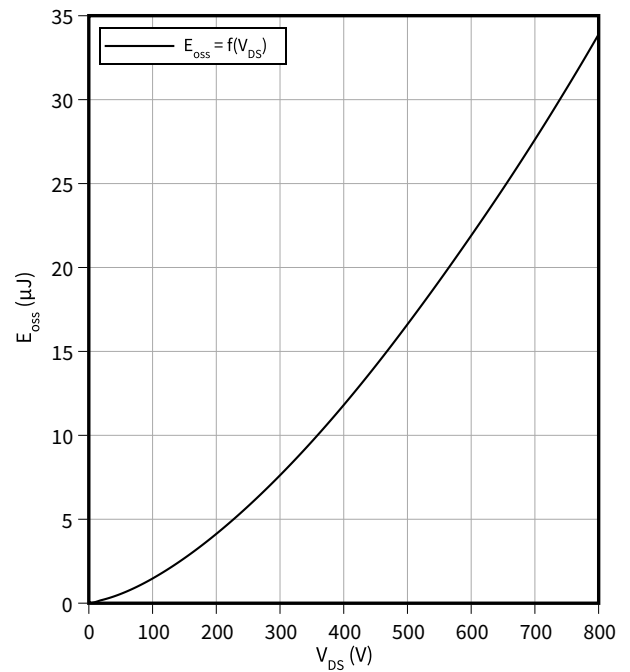
$$f = 100 \text{ kHz}, V_{GS} = 0 \text{ V}$$



Typical C_{oss} stored energy

$$E_{oss} = f(V_{DS})$$

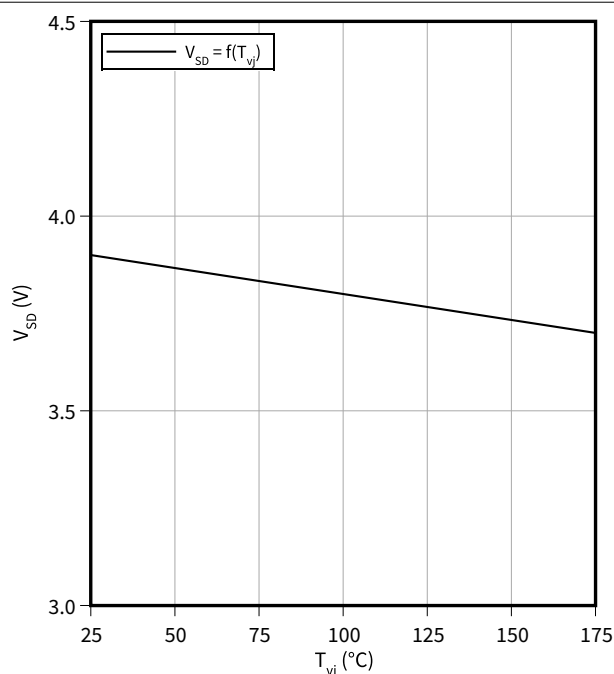
$$f = 100 \text{ kHz}$$



4 Characteristics diagrams

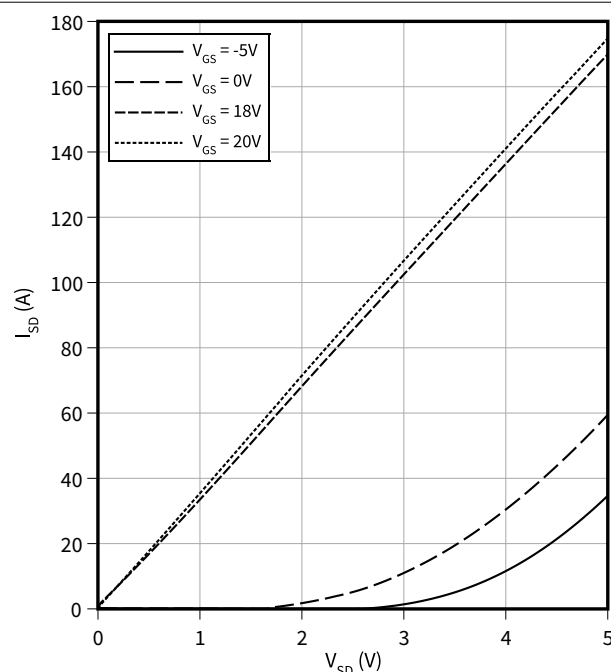
Typical reverse drain voltage as function of junction temperature

$V_{SD} = f(T_{vj})$
 $I_{SD} = 27 \text{ A}$, $V_{GS} = 0 \text{ V}$



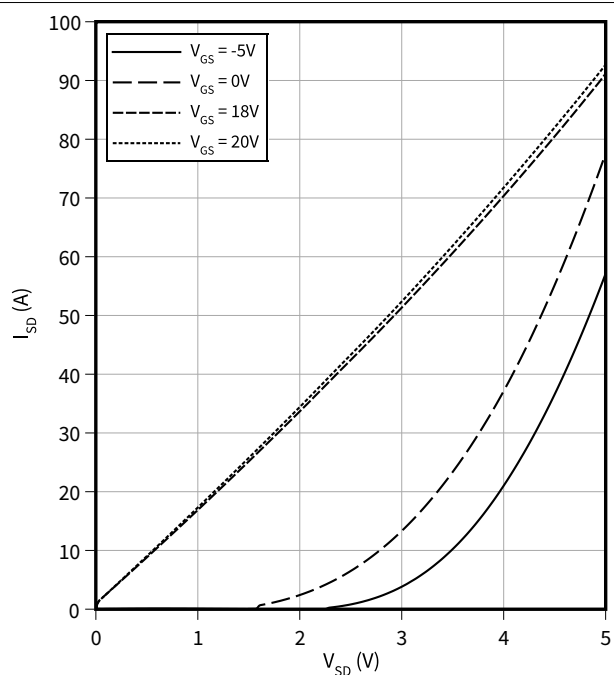
Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 25 \text{ }^\circ\text{C}$, $t_p = 20 \text{ } \mu\text{s}$



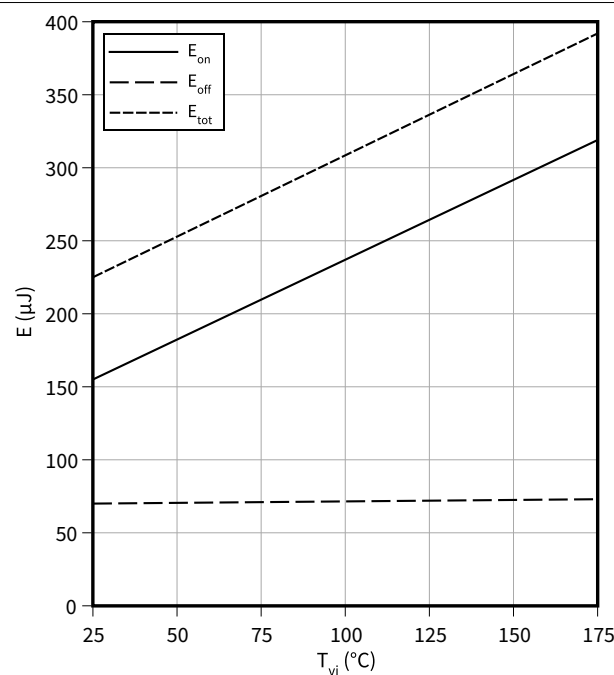
Typical reverse drain current as function of reverse drain voltage, V_{GS} as parameter

$I_{SD} = f(V_{SD})$
 $T_{vj} = 175 \text{ }^\circ\text{C}$, $t_p = 20 \text{ } \mu\text{s}$



Typical switching energy as a function of junction temperature, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0 \text{ V}$

$E = f(T_{vj})$
 $V_{GS} = 0/20 \text{ V}$, $I_D = 27 \text{ A}$, $R_{G,ext} = 2 \text{ } \Omega$, $V_{DD} = 800 \text{ V}$

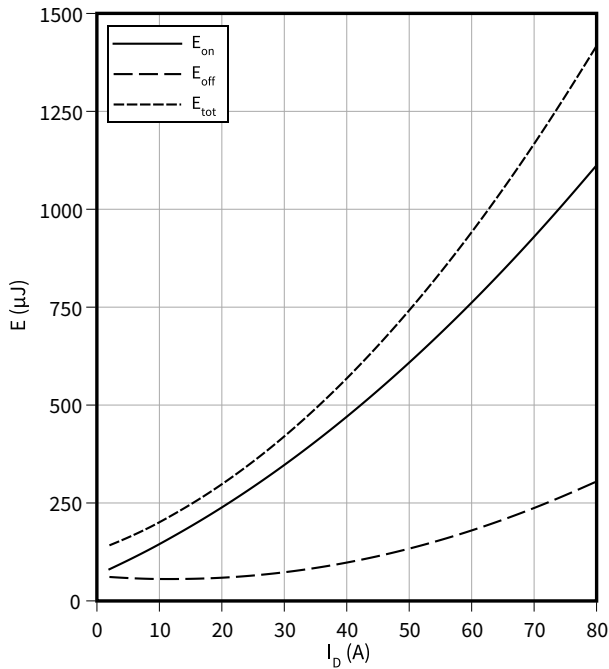


4 Characteristics diagrams

Typical switching energy as a function of drain current, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(I_D)$$

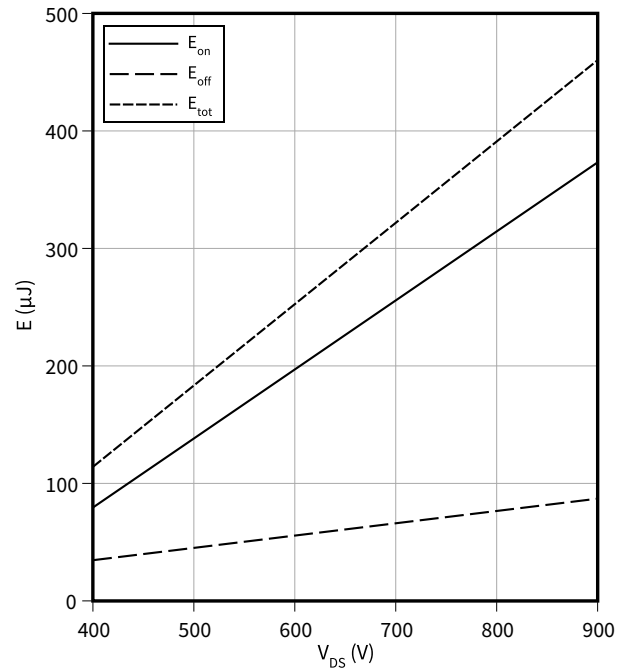
$V_{GS} = 0/20$ V, $T_{vj} = 175$ °C, $R_{G,ext} = 2$ Ω , $V_{DD} = 800$ V



Typical switching energy as a function of drain voltage, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(V_{DS})$$

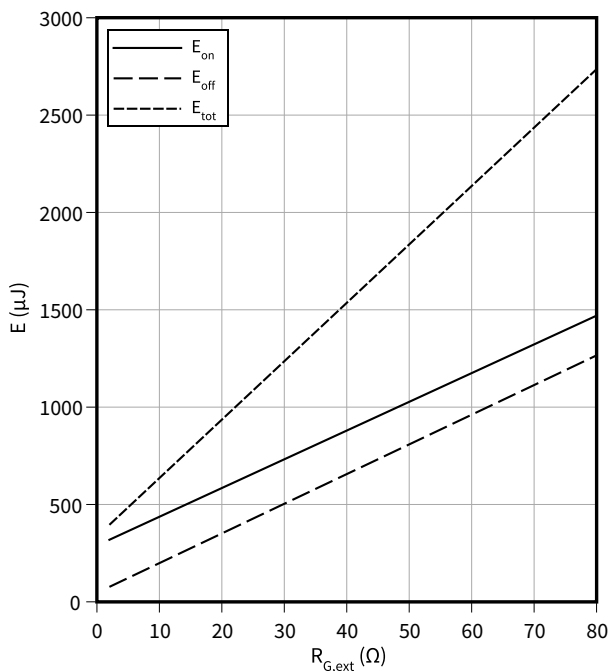
$V_{GS} = 0/20$ V, $I_D = 27$ A, $T_{vj} = 175$ °C, $R_{G,ext} = 2$ Ω



Typical switching energy as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$E = f(R_{G,ext})$$

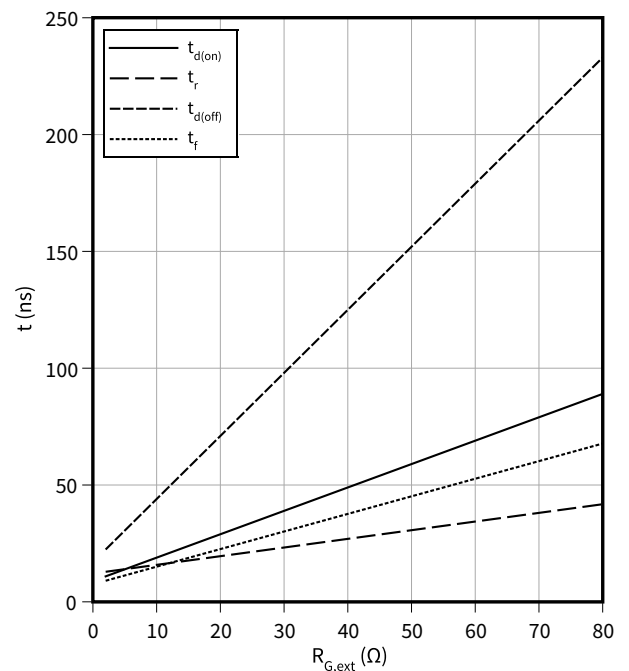
$V_{GS} = 0/20$ V, $I_D = 27$ A, $T_{vj} = 175$ °C, $V_{DD} = 800$ V



Typical switching times as a function of gate resistance, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0$ V

$$t = f(R_{G,ext})$$

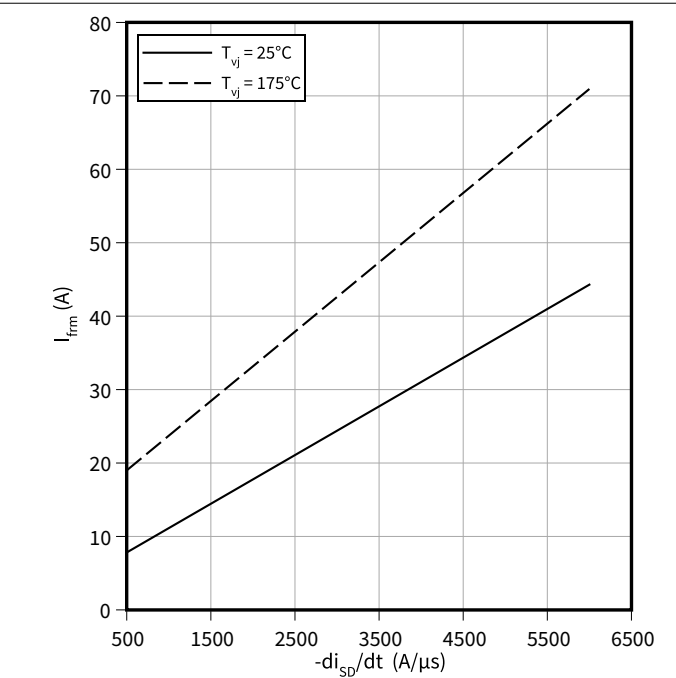
$V_{GS} = 0/20$ V, $I_D = 27$ A, $T_{vj} = 175$ °C, $V_{DD} = 800$ V



4 Characteristics diagrams

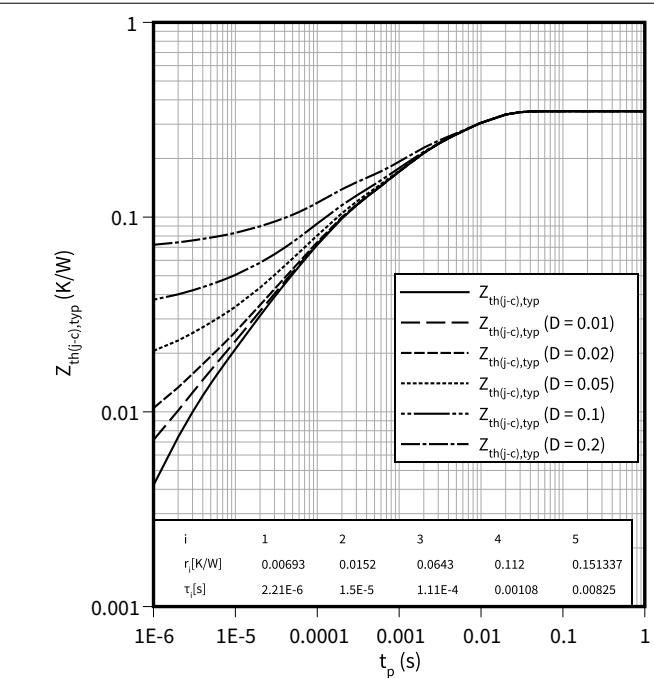
Typical reverse recovery current as a function of reverse drain current slope, test circuit in Fig. F, 2nd device own body diode: $V_{GS} = 0\text{ V}$

$I_{frm} = f(-di_{SD}/dt)$
 $V_{GS} = 0/20\text{ V}, I_{SD} = 27\text{ A}, V_{DD} = 800\text{ V}$



Typ. transient thermal impedance (MOSFET/diode)

$Z_{th(j-c),typ} = f(t_p)$
 $D = t_p/T$



5 Package outlines

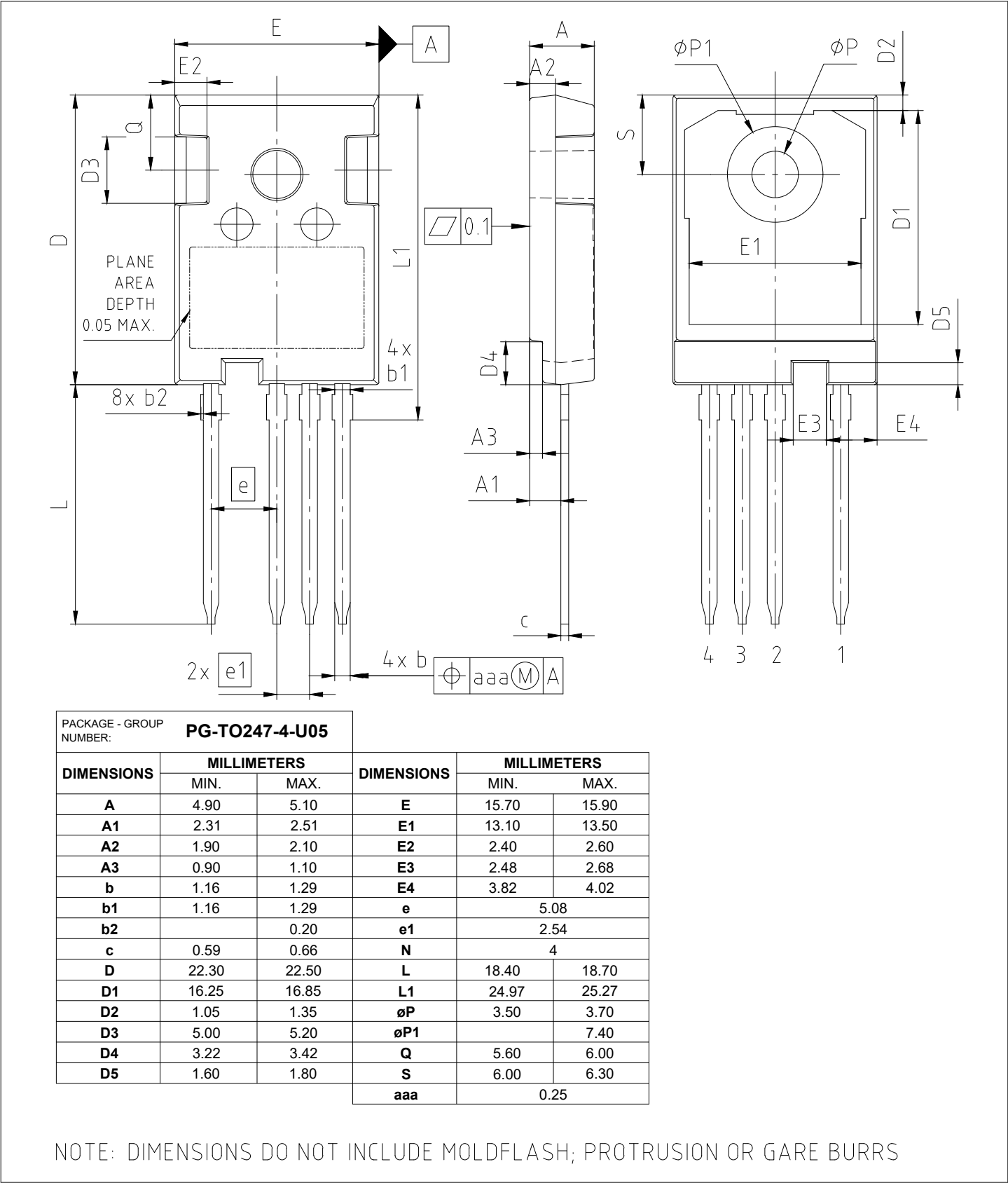


Figure 1

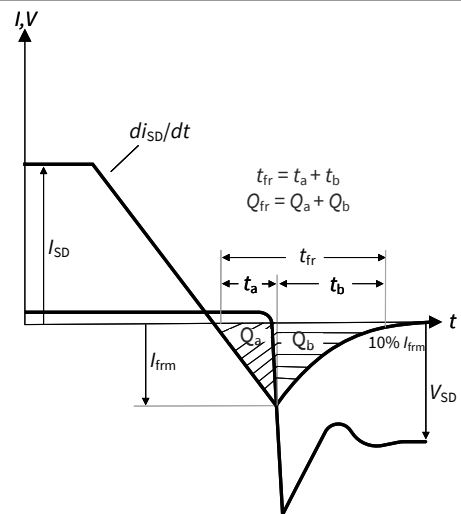
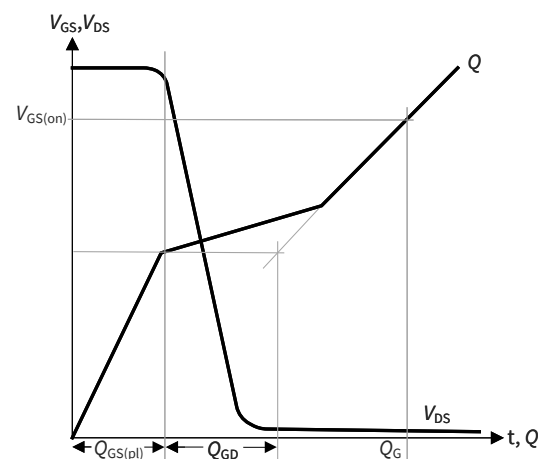
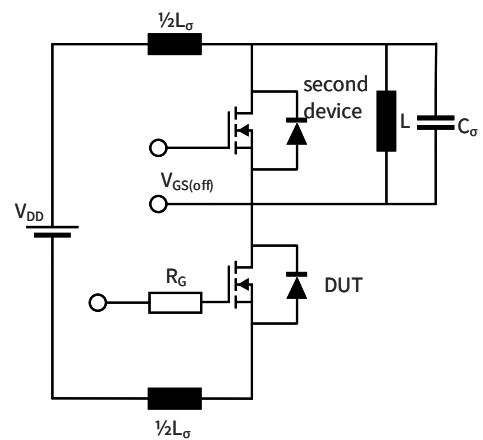


Figure B. **Definition of body diode switching characteristics**

Figure D. **Definition of QGD**Figure F. **Dynamic test circuit**

Revision history

Document revision	Date of release	Description of changes
0.10	2022-04-19	Target datasheet
0.20	2023-08-03	Preliminary datasheet
1.00	2023-12-01	Final datasheet
1.10	2025-10-15	Updated table values: g_{fs}, L_{σ} for switching parameters, $t_{d(on)}$, t_r, $t_{d(off)}$, t_f, E_{on}, E_{off}, E_{tot}, I_{SDC}, Q_{fr}, I_{frm}, condition d_{isd}/dt for Q_{fr} and I_{frm} Added values: creepage distance value on p.1, I_{sm} values for limited t_p Updated graphs: $I_{DS} = f(V_{DS})$, $R_{on}(T_{vj})$, $I_{DS}(V_{GS})$, $I_{SD} = f(V_{SD})$, $E = f(T_{vj})$, $E = f(RG_{ext})$, $E = f(I_D)$, $t_{sw} = f(RG_{ext})$, $Z_{th(j-c)} = f(t_p)$ Added graphs: $E_{sw} = f(V_{DS})$, $I_{frm} = f(di/dt)$ No change to the product, new/added values are based on additional assessments

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